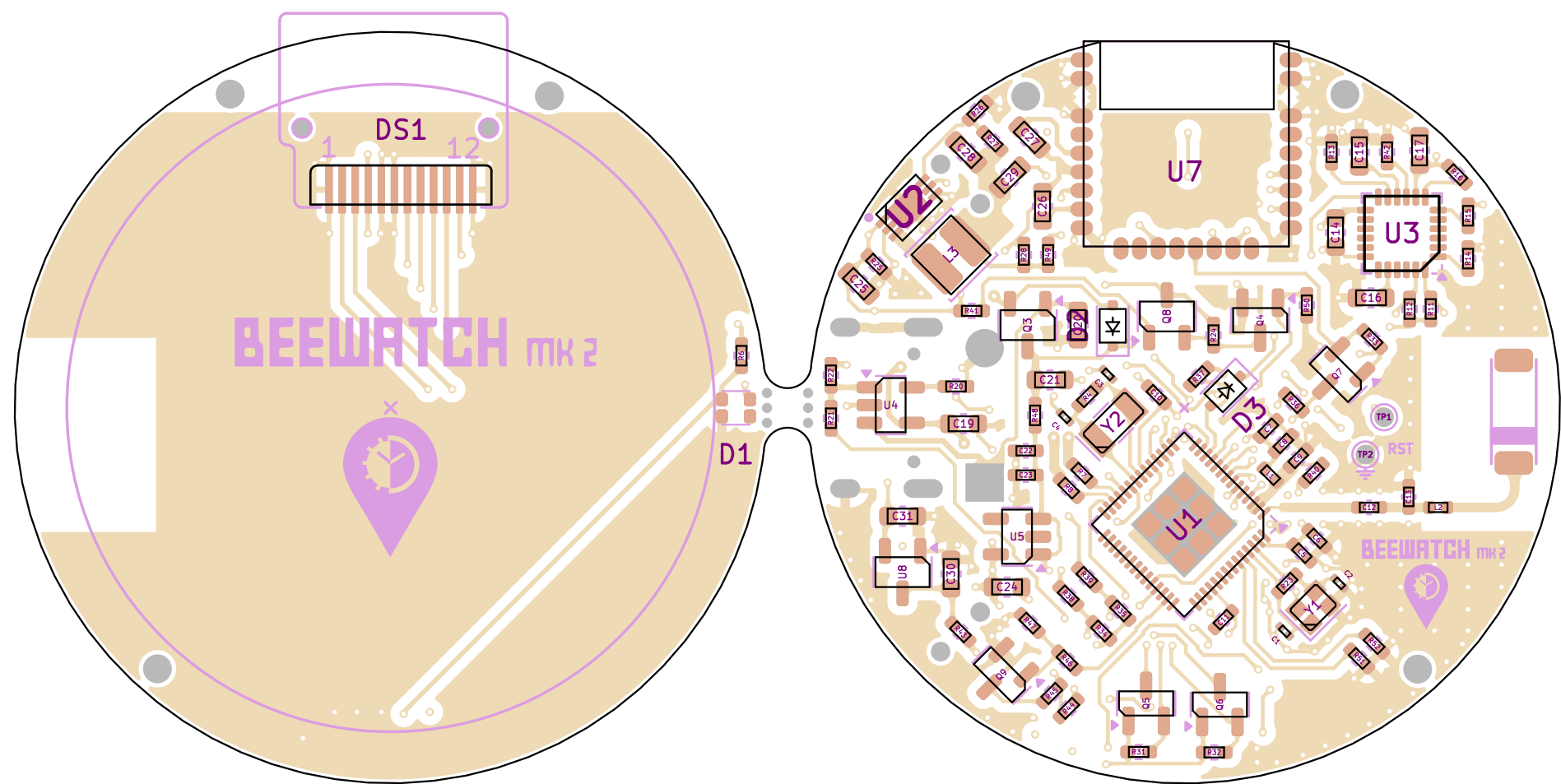
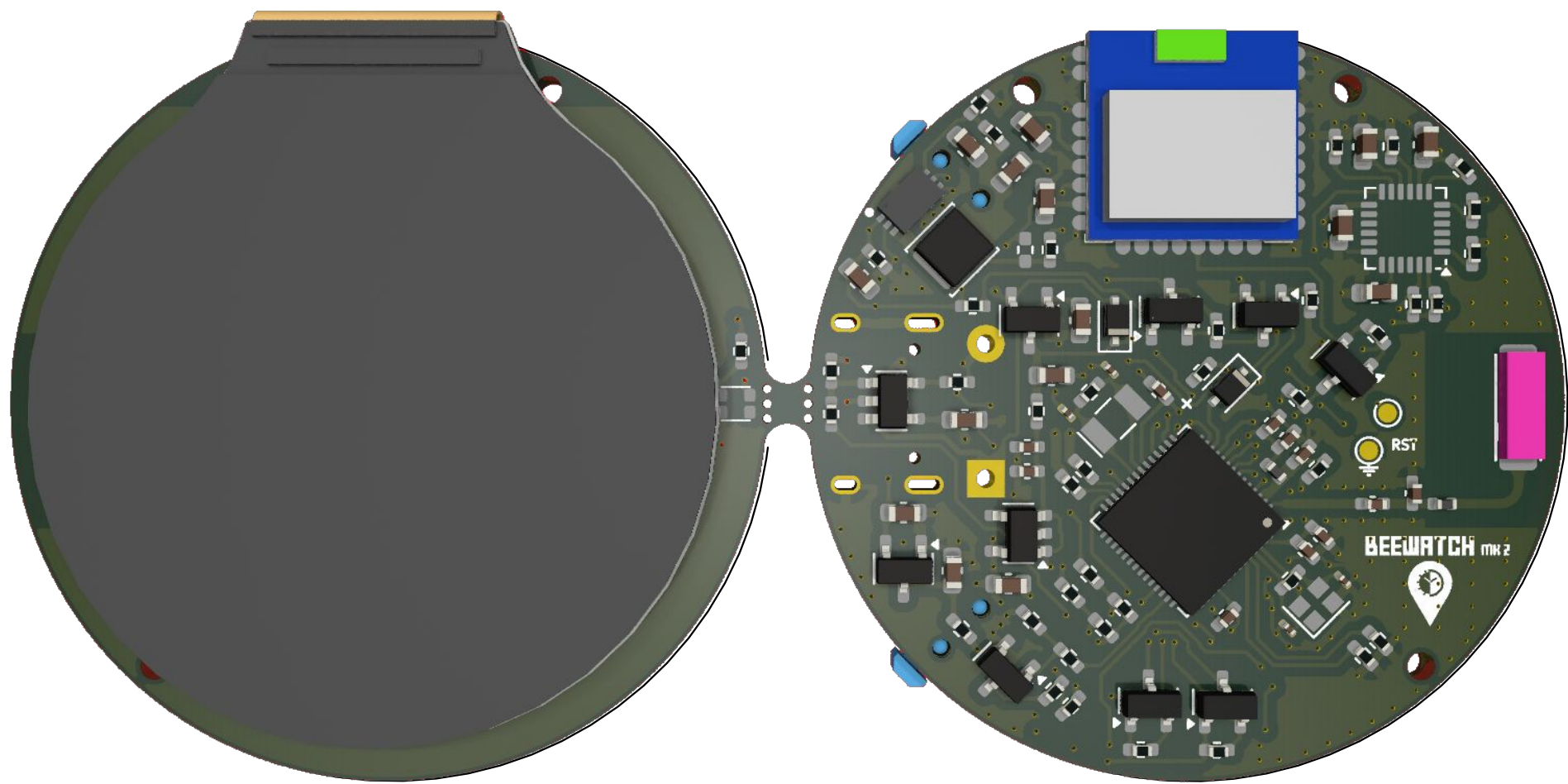


Top Assembly (Scale 1:3)



ASSEMBLY NOTES (UNLESS OTHERWISE SPECIFIED)

1. All components must be placed and soldered as per the latest Bill of Materials (BOM) and assembly drawings.
2. Unless otherwise specified, all polarized components (diodes, electrolytic capacitors, etc.) must be assembled with correct orientation.
3. Ensure correct placement and orientation of ICs, connectors, and LEDs as per silkscreen markings.
4. Clean the PCB after soldering to remove all flux residues and contaminants.
5. Use ESD-safe practices during handling and assembly of the PCB.
6. Do not substitute components without prior approval.
7. Verify all mechanical components (connectors, switches, etc.) for correct alignment and secure fitting.
8. Apply solder paste using the stencil provided or per Gerber paste layer.
9. Follow IPC-A-610 Class 2 (or Class 3, if applicable) workmanship standards.
10. All surface-mount components should be reflow soldered. Through-hole components should be hand-soldered unless specified otherwise.
11. No visible solder bridges, cold joints, or misalignments are allowed.
12. All assembled PCBs must pass visual inspection and functional testing (if applicable).
13. Include fiducials on board corners for pick-and-place machine alignment.
14. Do not apply conformal coating unless instructed.
15. Handle boards by the edges. Avoid touching component surfaces.

Bottom Assembly (Scale 1:3)

